

AUG 02 2004

TRANSMITTAL OF FORMAL DRAWINGS

Docket No.

YOR920030335US1 (16900)

IFW

PREVIOUS RE-APPLICATION  
RE-APPLICATION

Re Application Of: Diane C. Boyd, et al.

Application No.	Filing Date	Confirmation No.	Examiner	Customer No.	Group Art Unit
10/725,848	December 2, 2003	Unassigned	Unassigned	23389	Unassigned

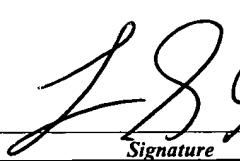
Invention: ULTRA-THIN Si MOSFET DEVICE STRUCTURE AND METHOD OF MANUFACTURE

Address to:

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Transmitted herewith are:

- 8 sheets of formal drawing(s) for this application.
- Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c).



Signature

Leslie S. Szivos, Ph.D.  
Registration No. 39,394

HAH:LSS:kc

Dated: July 29, 2004

I certify that this document and attached formal drawings  
are being deposited on 7/29/04 with  
the U.S. Postal Service as first class mail under 37 C.F.R. 1.8  
and addressed to the Commissioner for Patents, P.O. Box  
1450, Alexandria, VA 22313-1450.



Signature of Person Mailing Correspondence

Leslie S. Szivos, Ph.D.

Typed or Printed Name of Person Mailing Correspondence